

Title (en)

ELECTRICAL COMPONENT WITH THIN SOLDER RESIST LAYER AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ELEKTRISCHES BAUELEMENT MIT DÜNNER LOT-STOPP-SCHICHT UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

ÉLÉMENT ÉLECTRIQUE AVEC UNE COUCHE MINCE D'ARRÊT DE SOUDURE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 3381052 A1 20181003 (DE)

Application

EP 16762778 A 20160906

Priority

- DE 102015120647 A 20151127
- EP 2016070973 W 20160906

Abstract (en)

[origin: WO2017088998A1] The invention relates to an electrical module (EB) and to a method for producing an electrical module (EB). The module (EB) has a substrate (TR) with an upper layer (O) and a metal contact surface (MK) arranged thereon, as well as a solder resist layer (LSS) that covers part of the upper side (O), but not the contact surface (MK). The module (EB) also comprises an electrical component (EK) with a contact surface (KF) on the lower side and a solder bump connection (BU) that connects the two contact surfaces (MK, KF). The solder resist layer (O) has a maximum thickness of 200 nm and thereby simplifies subsequent method steps for the encapsulation of the module (EB) with a mould mass (MM).

IPC 8 full level

H01L 23/498 (2006.01); **B81C 3/00** (2006.01); **H01L 21/56** (2006.01); **H01L 21/60** (2006.01); **H01L 23/485** (2006.01)

CPC (source: EP KR US)

H01L 21/4846 (2013.01 - KR US); **H01L 21/4853** (2013.01 - US); **H01L 21/56** (2013.01 - EP US); **H01L 21/565** (2013.01 - US); **H01L 23/3121** (2013.01 - EP KR US); **H01L 23/49811** (2013.01 - US); **H01L 23/49838** (2013.01 - US); **H01L 23/49894** (2013.01 - EP KR US); **H01L 24/02** (2013.01 - EP KR US); **H01L 24/11** (2013.01 - EP KR US); **H01L 24/14** (2013.01 - KR); **H01L 24/16** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP KR US); **H01L 24/05** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H01L 2224/02375** (2013.01 - EP US); **H01L 2224/0239** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/10145** (2013.01 - EP US); **H01L 2224/10175** (2013.01 - EP US); **H01L 2224/1132** (2013.01 - EP US); **H01L 2224/1148** (2013.01 - EP US); **H01L 2224/11849** (2013.01 - EP US); **H01L 2224/131** (2013.01 - EP US); **H01L 2224/13294** (2013.01 - EP US); **H01L 2224/133** (2013.01 - EP US); **H01L 2224/16058** (2013.01 - EP US); **H01L 2224/16059** (2013.01 - EP US); **H01L 2224/16145** (2013.01 - EP US); **H01L 2224/16227** (2013.01 - US); **H01L 2224/16238** (2013.01 - EP US); **H01L 2224/81192** (2013.01 - EP US); **H01L 2224/81815** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/3841** (2013.01 - EP US)

Citation (search report)

See references of WO 2017088998A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2017088998 A1 20170601; BR 112018010666 A2 20181113; BR 112018010666 A8 20190226; CN 108369935 A 20180803; DE 102015120647 A1 20170601; DE 102015120647 B4 20171228; EP 3381052 A1 20181003; JP 2018536994 A 20181213; KR 20180088798 A 20180807; US 2018331062 A1 20181115

DOCDB simple family (application)

EP 2016070973 W 20160906; BR 112018010666 A 20160906; CN 201680062169 A 20160906; DE 102015120647 A 20151127; EP 16762778 A 20160906; JP 2018527165 A 20160906; KR 20187011776 A 20160906; US 201615776019 A 20160906